AMENDMENTS

In the Claims:

1. (Withdrawn) A method of fabricating an orifice plate for use in an ink jet printing system, comprising the steps of:

providing a substrate base;

applying a controlled-release layer to a surface of the substrate base; adherently coating a conductive metal layer on the controlled-release

layer;

layer;

creating at least one dielectric peg on a portion of the conductive metal

applying a nozzle layer on the conductive metal layer wherein the nozzle layer partially covers the at least one dielectric peg;

using photolithography to define a trench that covers the nozzles prior to formation of a second reinforcing layer;

removing the controlled-release layer to separate the orifice plate from the substrate base:

selectively etching the conductive metal layer from the nozzle layer to produce a completed multi-layer orifice plate.

- 2. (Withdrawn) A method as claimed in claim 1 wherein the substrate base comprises a metal substrate not attacked by chemicals used in electroforming processes.
- 3. (Withdrawn) A method as claimed in claim 1 wherein the substrate base comprises a chrome coated glass substrate.

- 4. (Withdrawn) A method as claimed in claim 1 wherein the controlled-release layer comprises an organic chemical layer.
- 5. (Withdrawn) A method as claimed in claim 4 wherein the organic chemical layer comprises a photoresist.
- 6. (Withdrawn) A method as claimed in claim 1 wherein the conductive metal layer comprises a copper layer.
- 7. (Withdrawn) A method as claimed in claim 1 wherein the conductive metal layer comprises a conductive layer having an approximate thickness of 0.1 micron.
- 8. (Withdrawn) A method as claimed in claim 1 wherein the step of adherently coating comprises the step of sputtering.
- 9. (Withdrawn) A method as claimed in claim 1 wherein the controlled-release layer comprises a controlled-release layer having an approximate thickness of 0.5 micron.
- 10. (Withdrawn) A method as claimed in claim 1 wherein the controlled-release layer comprises a controlled-release layer applied to the substrate base by spin coating.

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11. (Currently Amended) A mandrel for use in fabricating three dimensional electroformed structures comprising:

a substrate base;

a controlled-release layer applied to at least one surface of the substrate base; and

a conductive metal layer applied to the conductive-release layer wherein the conductive metal layer provides a surface upon which to electroform the structure [to which], the substrate base provides rigidity[,] to the mandrel, and the controlled-release layer provides sufficient adhesion to the substrate base to prevent the electroformed structure from delaminating from the substrate base during the electroforming processes and [still] <u>further</u> provide a means to remove the electroformed structure or the substrate base without damage to either the electroformed structure or the substrate base.

- 12. (Original) A mandrel as claimed in claim 11 wherein the substrate base comprises a metal substrate not attacked by chemicals used in electroforming processes.
- 13. (Original) A mandrel as claimed in claim 11 wherein the substrate base comprises a chrome coated glass substrate.
- 14. (Original) A mandrel as claimed in claim 11 wherein the controlled-release layer comprises an organic chemical layer.

- 15. (Original) A mandrel as claimed in claim 11 wherein the controlled-release layer comprises a controlled release layer whereby the electroformed substrate can be removed from the substrate base by chemically dissolving the controlled-release layer.
- 16. (Original) A mandrel as claimed in claim 11 wherein the controlled-release layer comprises a controlled-release layer whereby the electroformed substrate can be removed from the substrate base by melting the controlled-release layer.
- 17. (Original) A mandrel as claimed in claim 11 wherein the controlled-release layer comprises a brittle controlled-release layer.
- 18. (Original) A mandrel as claimed in claim 17 wherein the electroformed structure can be removed from the substrate base by fracturing the brittle controlled-release layer.
- 19. (Withdrawn) An orifice plate for use in an ink-jet printer made using a mandrel as claimed in claim 11.
- 20. (Withdrawn) A three dimensional structure made using a mandrel as claimed in claim 11.